

<b>Notice of References Cited</b>	Application/Control No. 10/806,680		Applicant(s)/Patent Under Reexamination ARORA ET AL.	
	Examiner Sun J. Lin		Art Unit 2825	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,424,141 B1	07-2002	Hollman et al.	324/158.1
*	B	US-6,430,729 B1	08-2002	Dewey et al.	716/4
	C	US-			
	D	US-			
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	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Kunikiyo et al., "Non-Destructive Inverse Modeling of Copper Interconnect Structure for 90 nm Technology Node", Sept. 2003, IEEE International Conference on Simulation Semiconductor Processes and Device, Paper Digest pp. 31 - 34.
	V	Agilent 4284 A Precision LCR Meter, Data Sheet, 2002, Agilent Technologies, Inc.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.